



2SK2545

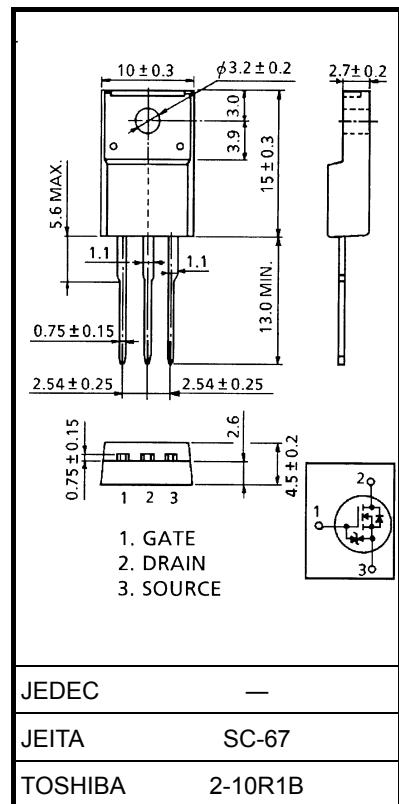
DC-DC Converter, Relay Drive and Motor Drive Applications

Unit: mm

- Low drain-source ON resistance : $R_{DS\ (ON)} = 0.9 \Omega\ (\text{typ.})$
- High forward transfer admittance : $|Y_{fs}| = 5.5 \text{ S} (\text{typ.})$
- Low leakage current : $I_{DSS} = 100 \mu\text{A} (\text{max}) (V_{DS} = 600 \text{ V})$
- Enhancement mode : $V_{th} = 2.0 \sim 4.0 \text{ V} (V_{DS} = 10 \text{ V}, I_D = 1 \text{ mA})$

Absolute Maximum Ratings ($T_a = 25^\circ\text{C}$)

Characteristics	Symbol	Rating	Unit
Drain-source voltage	V_{DSS}	600	V
Drain-gate voltage ($R_{GS} = 20 \text{ k}\Omega$)	V_{DGR}	600	V
Gate-source voltage	V_{GSS}	± 30	V
Drain current	DC (Note 1)	I_D	A
	Pulse (Note 1)	I_{DP}	A
Drain power dissipation ($T_c = 25^\circ\text{C}$)	P_D	40	W
Single pulse avalanche energy (Note 2)	E_{AS}	345	mJ
Avalanche current	I_{AR}	6	A
Repetitive avalanche energy (Note 3)	E_{AR}	4	mJ
Channel temperature	T_{ch}	150	$^\circ\text{C}$
Storage temperature range	T_{stg}	-55~150	$^\circ\text{C}$



Weight: 1.9 g (typ.)

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings. Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/Derating Concept and Methods) and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

Thermal Characteristics

Characteristics	Symbol	Max	Unit
Thermal resistance, channel to case	$R_{th\ (ch-c)}$	3.125	$^\circ\text{C} / \text{W}$
Thermal resistance, channel to ambient	$R_{th\ (ch-a)}$	62.5	$^\circ\text{C} / \text{W}$

Note 1: Ensure that the channel temperature does not exceed 150°C.

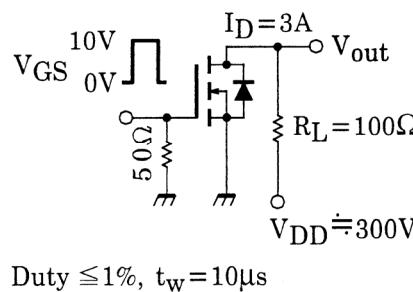
Note 2: $V_{DD} = 90 \text{ V}$, $T_{ch} = 25^\circ\text{C}$ (initial), $L = 16.8 \text{ mH}$, $R_G = 25 \Omega$, $I_{AR} = 6 \text{ A}$

Note 3: Repetitive rating: pulse width limited by maximum channel temperature

This transistor is an electrostatic-sensitive device.

Please handle with caution.

Electrical Characteristics (Ta = 25°C)

Characteristics	Symbol	Test Condition	Min	Typ.	Max	Unit
Gate leakage current	I _{GSS}	V _{GS} = ±25 V, V _{DS} = 0 V	—	—	±10	µA
Gate-source breakdown voltage	V (BR) GSS	I _G = ±10 µA, V _{GS} = 0 V	±30	—	—	V
Drain cut-off current	I _{DSS}	V _{DS} = 600 V, V _{GS} = 0 V	—	—	100	µA
Drain-source breakdown voltage	V (BR) DSS	I _D = 10 mA, V _{GS} = 0 V	600	—	—	V
Gate threshold voltage	V _{th}	V _{DS} = 10 V, I _D = 1 mA	2.0	—	4.0	V
Drain-source ON resistance	R _{D5} (ON)	V _{GS} = 10 V, I _D = 3 A	—	0.9	1.25	Ω
Forward transfer admittance	Y _{fs}	V _{DS} = 10 V, I _D = 3 A	2.0	5.5	—	S
Input capacitance	C _{iss}	V _{DS} = 10 V, V _{GS} = 0 V, f = 1 MHz	—	1300	—	pF
Reverse transfer capacitance	C _{rss}		—	130	—	
Output capacitance	C _{oss}		—	400	—	
Switching time	Rise time	t _r	 V _{GS} 10V 0V 50Ω	—	25	—
	Turn-on time	t _{on}		—	45	—
	Fall time	t _f		—	40	—
	Turn-off time	t _{off}		—	150	—
Total gate charge (Gate-source plus gate-drain)	Q _g	V _{DD} ≈ 400 V, V _{GS} = 10 V, I _D = 6 A	—	30	—	nC
Gate-source charge	Q _{gs}		—	18	—	
Gate-drain ("miller") charge	Q _{gd}		—	12	—	

Source-Drain Ratings and Characteristics (Ta = 25°C)

Characteristics	Symbol	Test Condition	Min	Typ.	Max	Unit
Continuous drain reverse current (Note 1)	I _{DR}	—	—	—	6	A
Pulse drain reverse current (Note 1)	I _{DRP}	—	—	—	24	A
Forward voltage (diode)	V _{DSF}	I _{DR} = 6 A, V _{GS} = 0 V	—	—	-1.7	V
Reverse recovery time	t _{rr}	I _{DR} = 6 A, V _{GS} = 0 V, dI _{DR} / dt = 100 A / µs	—	1000	—	ns
Reverse recovery charge	Q _{rr}		—	7.0	—	µC

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